

Schottky Barrier Diode DB3X501K0L

DB3X501K0L Silicon epitaxial planar type

For high speed switching circuits DB2J501 in Mini3 type package

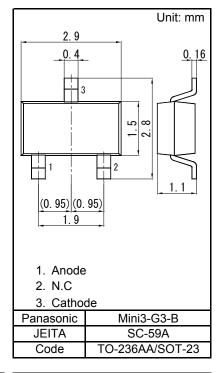
Features

- Short reverse recovery time trr
- Low terminal capacitance Ct
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol:4H

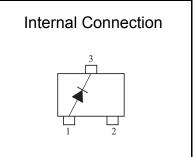
Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)



■ Absolute Maximum Ratings Ta = 25 °C

| 0 | | | |
|--|--------|-------------|------|
| Parameter | Symbol | Rating | Unit |
| Reverse voltage | VR | 50 | V |
| Repctitive peak reverse voltage | VRRM | 50 | V |
| Peak forward current | IFM | 300 | mA |
| Forward current (Average) | IF(AV) | 200 | mA |
| Non-repetitive peak forward surge current *1 | IFSM | 1 | А |
| Junction temperature | Tj | 125 | °C |
| Operating ambient temperature | Topr | -40 to +85 | °C |
| Storage temperature | Tstg | -55 to +125 | °C |
| | | | |



Note: *1 50 Hz sine wave 1 cycle (Non-repetitive peak current)

Panasonic

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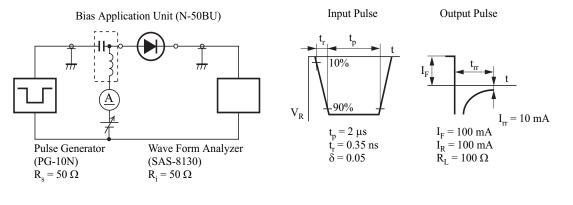
■ Electrical Characteristics Ta = 25 °C ± 3 °C

| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|-------------------------------------|--------|--|-----|-----|------|------|
| Forward voltage | VF1 | IF = 30 mA | | | 0.36 | V |
| | VF2 | IF = 200 mA | | | 0.55 | V |
| Reverse current | IR | VR = 50 V | | | 200 | μA |
| Terminal capacitance | Ct | VR = 10 V, f = 1 MHz | | 4 | | pF |
| Reverse recovery time ^{*1} | trr | IF = IR = 100 mA, Irr = 10 mA, RL = 100 Ω | | 1.6 | | ns |

Note: 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

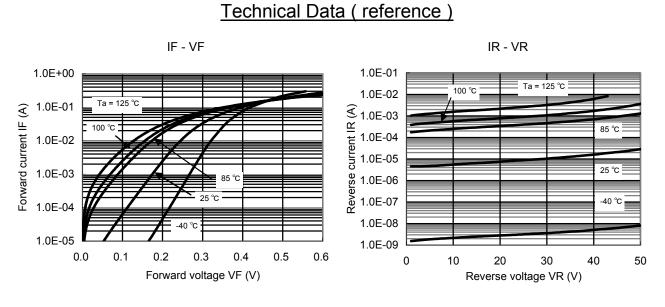
2. Schottky diode is frail with static electricity, and it should be kept in safety from shock of static electricity and static electricity level.

- 3. Absolute frequency of input and output is 1 000 MHz.
- 4. *1 : trr measurement circuit

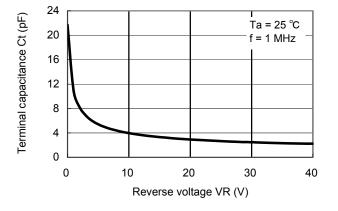


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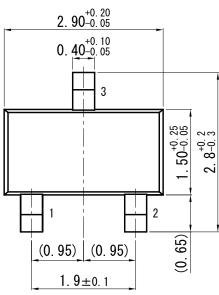
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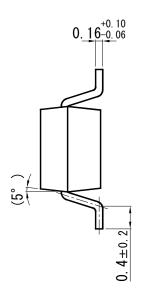


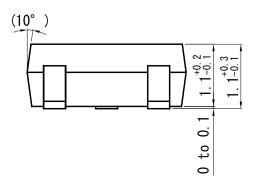
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Unit: mm

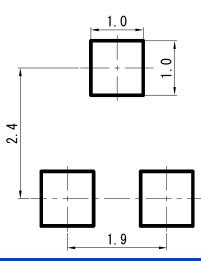
Mini3-G3-B







Land Pattern (Reference) (Unit: mm)



Established : 2010-02-24 Revised : 2013-12-13

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